

PCN# : P259A Issue Date : Jul. 10, 2012

DESIGN/PROCESS CHANGE NOTIFICATION

This is to inform you that a change is being made to the products listed below.

Unless otherwise indicated in the details of this notification, the identified change will have no impact on product quality, reliability, electrical, visual or mechanical performance and affected products will remain fully compliant to all published specifications. Products incorporating this change may be shipped interchangeably with existing unchanged products.

This change is planned to take effect in 90 calendar days from the date of this notification. Please work with your local Fairchild Sales Representative to manage your inventory of unchanged product if your evaluation of this change will require more than 90 calendar days.

Please contact your local Customer Quality Engineer within 30 days of receipt of this notification if you require any additional data or samples. Alternatively, you may send an email request for data, samples or other information to PCNSupport@fairchildsemi.com.

Implementation of change:

Expected First Shipment Date for Changed Product : Oct. 08, 2012

Expected First Date Code of Changed Product :1230

Description of Change (From) : Products assembled in the SPM5 package using the currently qualified bonding wire (1.3 mil Au wire).

Description of Change (To) : Products assembled in the SPM5 package using the new alternative bonding wire materials (1.5 mil Cu wire).

Reason for Change:

This is a change in bonding wire used for Fairchild products assembled in the SPM5 package. There are no changes to the currently approved assembly facilities or any other materials used to produce these products. Products will continue to meet all data sheet parameters and mechanical dimensions. Quality and reliability will remain at the highest standards already demonstrated with Fairchild's existing SPM5 products. If you require data or samples to evaluate this change, please contact Fairchild Semiconductor within 30 days of receipt of this notification. Unnecessary delays in requesting data or samples may limit Fairchild's ability to provide a continuous supply of product. Requests for samples or data received more than 90 days after receipt of this notification. Please work with your local Fairchild sales representative to place orders for sufficient quantities of unchanged product to support your manufacturing needs if your evaluation of this change will require more than 90 calendar days.



Affected Product(s):

FSB50250	FSB50250UD	FSB50250US
FSB50250UTD	FSB50325T	FSB50450
FSB50450S	FSB50450TB2	FSB50450UD
FSB50450US	FSB50550T	FSB50550TB2
FSB50550US	FSB50550UTD	FSB50825TB
FSB50825TB2	FSB50825US	FSB52006S
FTBV1P5SH50U	FTBV1SH25U	FTBV1SH25X
FTBV1SH50U	FTBV1SH50X	FTBVP5SH50U
FTBVP5SH50X	NBC9610	NBC9611
NBC9612	NBC9613	NBC9614
NBC9615	NBC9616	

Qualification Plan	Device	Package	Process	No. of Lots	
Q20120173	FSB50550T	SPM5 - DIP	Module	3	

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Cycle	-65°C to 150 °C	JESD22- A104	200, 500 cycles	0/75
Power Cycle	100°C	Mil Std 750 Method 1037	15kcycles	0/15
Temperature Humidity Bias Test	85°C, 85%,VDD = 100 V,VCC=15V	JESD22- A101	168, 500, 1000hrs	0/75
High Temperature Storage Life	150°C	JESD22- A103	168, 500, 1k hrs	0/75

Qualification Plan	Device	Package	Process	No. of Lots
Q20120173	FSB50550US	SPM5 - SMD	Module	3

Test Description:	Condition:	Standard :	Duration:	Results:
Temperature Cycle	-40°C to 125 °C	JESD22- A104	200 cycles	0/75
Power Cycle	100°C	Mil Std 750 Method 1037	15kcycles	0/15
Temperature Humidity Bias Test	85°C, 85%,VDD = 100 V,VCC=15V	JESD22- A101	168, 500, 1000hrs	0/75
High Temperature Storage Life	150°C	JESD22- A103	168, 500, 1k hrs	0/75